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# Low Skew, 1-to-18 LVPECL-TO-LVCMOS / LVTTL Fanout Buffer

**DATASHEET** 

#### GENERAL DESCRIPTION

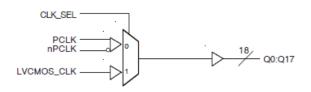
The 83940D is a low skew, 1-to-18 LVPECL-to-LVC-MOS/LVTTL Fanout Buffer. The 83940D has two selectable clock inputs. The PCLK, nPCLK pair can accept LVPECL, CML, or SSTL input levels. The LVCMOS\_CLK can accept LVCMOS or LVTTL input levels. The low impedance LVCMOS/LVTTL outputs are designed to drive  $50\Omega$  series or parallel terminated transmission lines.

The 83940D is characterized at full 3.3V and 2.5V or mixed3.3V core, 2.5V output operating supply modes. Guaranteed output and part-to-part skew characteristics make the 83940D ideal for those clock distribution applications demanding well defined performance and repeatability.

#### **FEATURES**

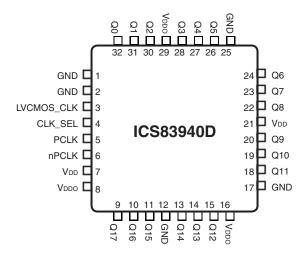
- 18 LVCMOS/LVTTL outputs
- Selectable LVCMOS\_CLK or LVPECL clock inputs
- PCLK, nPCLK supports the following input types: LVPECL, CML, SSTL
- LVCMOS\_CLK accepts the following input levels: LVCMOS or LVTTL
- Maximum output frequency: 250MHz
- Output skew: 150ps (maximum)
- Part to part skew: 750ps (maximum)
- Additive phase jitter, RMS: < 0.03ps (typical)
- Full 3.3V and 2.5V or mixed 3.3V core, 2.5V output supply modes
- 0°C to 70°C ambient operating temperature
- · Lead-Free package available

#### **BLOCK DIAGRAM**



#### PIN ASSIGNMENT

1



32-Lead LQFP
7mm x 7mm x 1.4mm package body
Y Pacakge
Top View



TABLE 1. PIN DESCRIPTIONS

Number	Name	Т	уре	Description
1, 2, 12, 17, 25	GND	Power		Power supply ground.
3	LVCMOS_CLK	Input	Pulldown	Clock input. LVCMOS / LVTTL interface levels.
4	CLK_SEL	Input	Pulldown	Clock select input. Selects LVCMOS / LVTTL clock input when HIGH. Selects PCLK, nPCLK inputs when LOW. LVCMOS / LVTTL interface levels.
5	PCLK	Input	Pulldown	Non-inverting differential LVPECL clock input.
6	nPCLK	Input		Inverting differential LVPECL clock input. $V_{DD}/2$ default when left floating.
7, 21	$V_{_{\mathrm{DD}}}$	Power		Core supply pins.
8, 16, 29	$V_{\scriptscriptstyle DDO}$	Power		Output supply pins.
9, 10, 11, 13, 14, 15, 18, 19, 20, 22, 23, 24, 26, 27, 28, 30, 31, 32	Q17, Q16, Q15, Q14, Q13, Q12, Q11, Q10, Q9, Q8, Q7, Q6, Q5, Q4, Q3, Q2, Q1, Q0	Output		Clock outputs. LVCMOS / LVTTL interface levels.

NOTE: Pullup and Pulldown refers to internal input resistors. See Table 2, Pin Characteristics, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C <sub>IN</sub>	Input Capacitance			4		pF
C <sub>PD</sub>	Power Dissipation Capacitance (per output)			6		pF
R <sub>PULLup</sub>	Input Pullup Resistor			51		ΚΩ
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			51		ΚΩ
R <sub>out</sub>	Output Impedance		18		28	Ω

TABLE 3A. CLOCK SELECT FUNCTION TABLE

Control Input	Clock				
CLK_SEL	PCLK, nPCLK	LVCMOS_CLK			
0	Selected	De-selected			
1	De-selected	Selected			

TABLE 3B. CLOCK INPUT FUNCTION TABLE

	Int	outs		Outputs	Input to Output Mode	Polarity
CLK_SEL	LVCMOS_CLK	PCLK	nPCLK	Q0:Q17	input to Output Mode	Polarity
0	_	0	1	LOW	Differential to Single Ended	Non Inverting
0	_	1	0	HIGH	Differential to Single Ended	Non Inverting
0	_	0	Biased; NOTE 1	LOW	Single Ended to Single Ended	Non Inverting
0	_	1	Biased; NOTE 1	HIGH	Single Ended to Single Ended	Non Inverting
0	_	Biased; NOTE 1	0	HIGH	Single Ended to Single Ended	Inverting
0	_	Biased; NOTE 1	1	LOW	Single Ended to Single Ended	Inverting
1	0	_	_	LOW	Single Ended to Single Ended	Non Inverting
1	1	_	_	HIGH	Single Ended to Single Ended	Non Inverting

NOTE 1: Please refer to the Application Information section, "Wiring the Differential Input to Accept Single Ended Levels".

2



#### **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage,  $V_{DD}$  3.6V

Inputs,  $V_{l}$  -0.3V to  $V_{DD}$  + 0.3V

Outputs,  $V_{O}$  -0.3V to  $V_{DDO}$  + 0.3V

Input Current, I<sub>IN</sub> ±20mA

Storage Temperature,  $T_{STG}$  -40°C to 125°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.



Table 4A. DC Characteristics,  $V_{DD} = V_{DDO} = 3.3V \pm 5\%$ , Ta =  $0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	LVCMOS_CLK		2.4		$V_{_{\mathrm{DD}}}$	V
V <sub>IL</sub>	Input Low Voltage	LVCMOS_CLK				0.8	V
V <sub>PP</sub>	Peak-to-Peak Input Voltage	PCLK, nPCLK		500		1000	mV
V <sub>CMR</sub>	Input Common Mode Voltage; NOTE 1, 2			V <sub>DD</sub> - 1.4		V <sub>DD</sub> - 0.6	V
I <sub>IN</sub>	Input Current					±200	μA
V <sub>OH</sub>	Output High Voltage		I <sub>OH</sub> = -20mA	2.4			V
V <sub>OL</sub>	Output Low Voltage		I <sub>OL</sub> = 20mA			0.5	V
I <sub>DD</sub>	Core Supply Current					25	mA

NOTE 1: For single ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{\text{DD}}$  + 0.3V.

NOTE 2: Common mode voltage is defined as  $\rm V_{\rm \tiny IH}$ 

Table 5A. AC Characteristics,  $V^{}_{DD} = V^{}_{DDO} = 3.3 V \pm 5\%, \, Ta = 0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					250	MHz
+	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	f ≤ 150MHz	1.6		3.0	ns
t <sub>pLH</sub>	Fropagation Delay	LVCMOS_CLK; NOTE 2, 5	f ≤ 150MHz	1.8		3.0	ns
+	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	f > 150MHz	1.6		3.3	ns
t <sub>pLH</sub>	Propagation Delay	LVCMOS_CLK; NOTE 2, 5	f > 150MHz	1.8		3.2	ns
tal(a)	Output Skew;	PCLK, nPCLK	Measured on			150	ps
NOTE 3, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			150	ps	
t-1-/\	Part-to-Part Skew;	PCLK, nPCLK	f ≤ 150MHz			1.4	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f ≤ 150MHz			1.2	ns
t-1-/\	Part-to-Part Skew;	PCLK, nPCLK	f > 150MHz			1.7	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f > 150MHz			1.4	ns
+=l(/==)	Part-to-Part Skew;	PCLK, nPCLK	Measured on			850	ps
tsk(pp)	NOTE 4, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			750	ps
tjit	Buffer Additive Phas refer to Additive Pha NOTE 7				0.03		ps
$t_R/t_F$	Output Rise/Fall Tim	e	0.5 to 2.4V	0.3		1.1	ns
	Output Duty Ovala		f < 134MHz	45	50	55	%
odc	Output Duty Cycle		$134MHz \le f \le 250MHz$	40	50	60	%

All parameters measured at 200MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output V<sub>ppo</sub>/2.

NOTE 2: Measured from  $V_{DD}/2$  to  $V_{DDO}/2$ .

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at Vpno/2.

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages, same temperature,

and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{DDO}/2$ .

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{DDO}/2$ .

NOTE 7: Driving only one input clock.



Table 4B. DC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 2.5V \pm 5\%$ , Ta =  $0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter	Parameter		Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	LVCMOS_CLK		2.4		$V_{_{\mathrm{DD}}}$	V
V <sub>IL</sub>	Input Low Voltage	LVCMOS_CLK				0.8	V
V <sub>PP</sub>	Peak-to-Peak Input Voltage	PCLK, nPCLK		300		1000	mV
V <sub>CMR</sub>	Input Common Mode Voltage; NOTE 1, 2	PCLK, nPCLK		V <sub>DD</sub> - 1.4		V <sub>DD</sub> - 0.6	V
I <sub>IN</sub>	Input Current					±200	μΑ
V <sub>OH</sub>	Output High Voltage		I <sub>OH</sub> = -20mA	1.8			V
V <sub>OL</sub>	Output Low Voltage		I <sub>OL</sub> = 20mA			0.5	V
I <sub>DD</sub>	Core Supply Current					25	mA

NOTE 1: For single ended applications, the maximum input voltage for PCLK, nPCLK is V<sub>nn</sub> + 0.3V.

NOTE 2: Common mode voltage is defined as V<sub>IH</sub>.

Table 5B. AC Characteristics,  $V_{DD} = 3.3V \pm 5\%$ ,  $V_{DDO} = 2.5V \pm 5\%$ , Ta =  $0^{\circ}$  to  $70^{\circ}$ 

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					250	MHz
+	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	f ≤ 150MHz	1.7		3.2	ns
t <sub>pLH</sub>	Propagation Delay	LVCMOS_CLK; NOTE 2, 5	f ≤ 150MHz	1.7		3.0	ns
+	Propagation Delay	PCLK, nPCLK; NOTE 1, 5	f > 150MHz	1.6		3.4	ns
t <sub>pLH</sub>	Propagation Delay	LVCMOS_CLK; NOTE 2, 5	f > 150MHz	1.8		3.3	ns
tol(a)	Output Skew;	put Skew; PCLK, nPCLK Measured on				150	ps
tsk(o)	NOTE 3, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			150	ps
t-1-()	Part-to-Part Skew;	PCLK, nPCLK	f ≤ 150MHz			1.5	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f ≤ 150MHz			1.3	ns
	Part-to-Part Skew;	PCLK, nPCLK	f > 150MHz			1.8	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f > 150MHz			1.5	ns
t-1-/\	Part-to-Part Skew;	PCLK, nPCLK	Measured on			850	ps
tsk(pp)	NOTE 4, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			750	ps
tjit	Buffer Additive Phas refer to Additive Pha NOTE 7				0.03		ps
t <sub>R</sub> /t <sub>F</sub>	Output Rise/Fall Tim	ne	0.5 to 1.8V	0.3		1.2	ns
odc	Output Duty Cycle		f < 134MHz	45	50	55	%

All parameters measured at 200MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output V<sub>DDO</sub>/2.

NOTE 2: Measured from  $V_{DD}/2$  to  $V_{DDO}/2$ .

NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at V<sub>DDO</sub>/2.

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages, same temperature,

and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{\rm DDO}/2$ .

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges, and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at  $V_{DDO}/2$ .

NOTE 7: Driving only one input clock.



Table 4C. DC Characteristics,  $V_{DD} = V_{DDO} = 2.5V \pm 5\%$ , Ta = 0° to 70°

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
V <sub>IH</sub>	Input High Voltage	LVCMOS_CLK		2		V <sub>DD</sub>	V
V <sub>IL</sub>	Input Low Voltage	LVCMOS_CLK				0.8	٧
V <sub>PP</sub>	Peak-to-Peak Input Voltage	PCLK, nPCLK		300		1000	mV
V <sub>CMR</sub>	Input Common Mode Voltage; NOTE 1, 2	PCLK, nPCLK		V <sub>DD</sub> - 1.4		V <sub>DD</sub> - 0.6	٧
I <sub>IN</sub>	Input Current					±200	μA
V <sub>OH</sub>	Output High Voltage		I <sub>OH</sub> = -12mA	1.8			٧
V <sub>OL</sub>	Output Low Voltage		I <sub>OL</sub> = 12mA			0.5	٧
I <sub>DD</sub>	Core Supply Current					25	mA

NOTE 1: For single ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{DD}$  + 0.3V.

NOTE 2: Common mode voltage is defined as  $V_{\rm in}$ .

Table 5C. AC Characteristics,  $V_{DD} = V_{DDO} = 2.5V \pm 5\%$ , Ta = 0° to 70°

Symbol	Parameter		Test Conditions	Minimum	Typical	Maximum	Units
f <sub>MAX</sub>	Output Frequency					200	MHz
+	Propagation Delay;	PCLK, nPCLK; NOTE 1, 5	f ≤ 150MHz	1.2		3.8	ns
<b>L</b> pLH	Fropagation Delay,	LVCMOS_CLK; NOTE 2, 5	f ≤ 150MHz	1.5		3.2	ns
+	Branagation Dalay	PCLK, nPCLK; NOTE 1, 5	f > 150MHz	1.5		3.7	ns
<b>L</b> pLH	Propagation Delay;	LVCMOS_CLK; NOTE 2, 5	f > 150MHz	2		3.6	ns
tal(a)	Output Skew;	PCLK, nPCLK	Measured on			200	ps
tsk(o)	NOTE 3, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			200	ps
+ - I - ( )	Part-to-Part Skew;	PCLK, nPCLK	f ≤ 150MHz			2.6	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f ≤ 150MHz			1.7	ns
t - I - ( )	Part-to-Part Skew;	PCLK, nPCLK	f > 150MHz			2.2	ns
tsk(pp)	NOTE 6	LVCMOS_CLK	f > 150MHz			1.7	ns
4-1-()	Part-to-Part Skew;	PCLK, nPCLK	Measured on			1.2	ns
tsk(pp)	NOTE 4, 5	LVCMOS_CLK	rising edge @V <sub>DDO</sub> /2			1.0	ns
tjit	Buffer Additive Phas refer to Additive Pha NOTE 7				0.03		ps
t <sub>R</sub> /t <sub>F</sub>	Output Rise/Fall Tim	е	0.5 to 1.8V	0.3		1.2	ns
odc	Output Duty Cycle		f < 134MHz	45		55	%

All parameters measured at 200MHz unless noted otherwise.

NOTE 1: Measured from the differential input crossing point to the output  $V_{DDO}/2$ .

NOTE 2: Measured from  $V_{DD}/2$  to  $V_{DDO}/2$ . NOTE 3: Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at  $V_{DDO}/2$ .

NOTE 4: Defined as skew between outputs on different devices operating at the same supply voltages, same temperature,

and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V<sub>npq</sub>/2.

NOTE 5: This parameter is defined in accordance with JEDEC Standard 65.

NOTE 6: Defined as skew between outputs on different devices, across temperature and voltage ranges,

and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at V\_DDG/2.

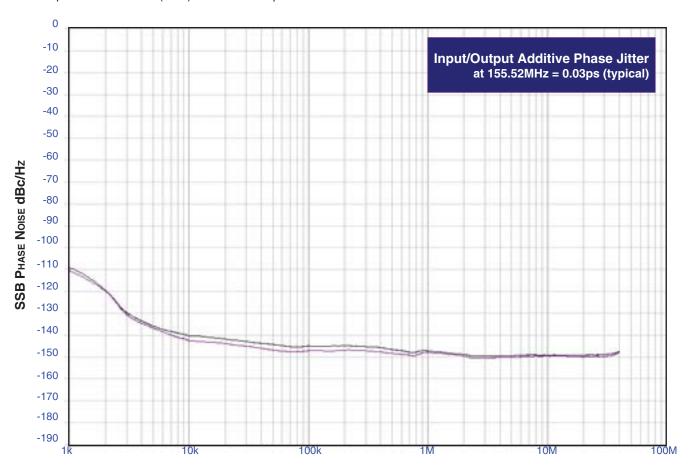
NOTE 7 Driving only one input clock.



#### **ADDITIVE PHASE JITTER**

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the *dBc Phase Noise*. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in the

1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a *dBc* value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



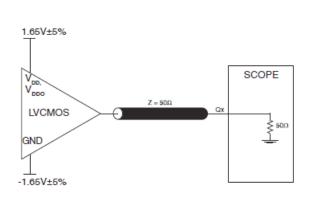
OFFSET FROM CARRIER FREQUENCY (Hz)

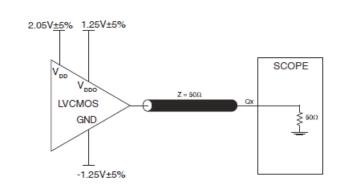
As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The

device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependant on the input source and measurement equipment.



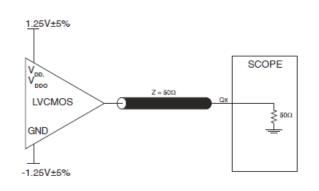
## PARAMETER MEASUREMENT INFORMATION

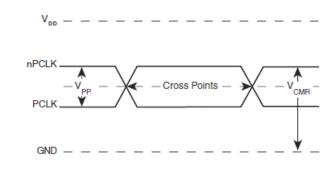




#### 3.3V CORE/3.3V OUTPUT LOAD AC TEST CIRCUIT

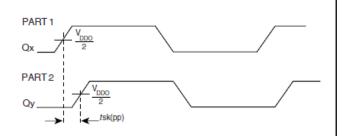
#### 3.3V Core/2.5V OUTPUT LOAD AC TEST CIRCUIT

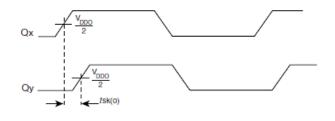




#### 2.5V OUTPUT LOAD AC TEST CIRCUIT

#### DIFFERENTIAL INPUT LEVEL

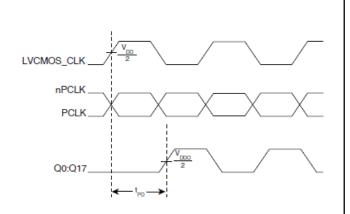


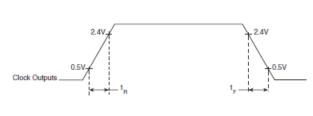


#### PART-TO-PART SKEW

**OUTPUT SKEW** 

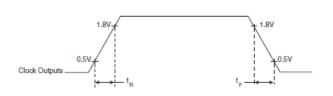






#### PROPAGATION DELAY

#### 3.3V OUTPUT RISE/FALL TIME



#### 2.5V OUTPUT RISE/FALL TIME

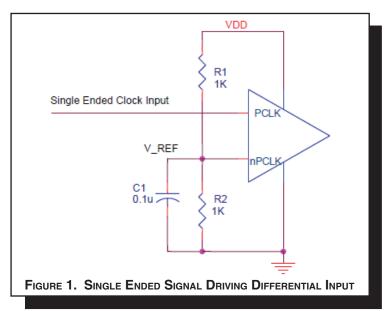


### **APPLICATION INFORMATION**

#### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_REF = V_{DD}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the V\_REF in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{DD}\!=\!3.3V$ , V\_REF should be 1.25V and R2/R1 = 0.609.





#### LVPECL CLOCK INPUT INTERFACE

The PCLK /nPCLK accepts LVPECL, CML, SSTL and other differential signals. Both V<sub>SWING</sub> and V<sub>OH</sub> must meet the V<sub>PP</sub> and V<sub>CMR</sub> input requirements. *Figures 2A to 2F* show interface examples for the PCLK/nPCLK input driven by the most common driver types. The input interfaces suggested here are examples

only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.

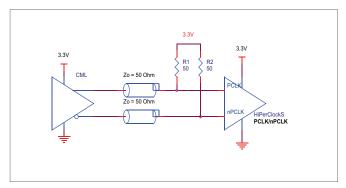


FIGURE 2A. PCLK/nPCLK INPUT DRIVEN
BY AN OPEN COLLECTOR CML DRIVER

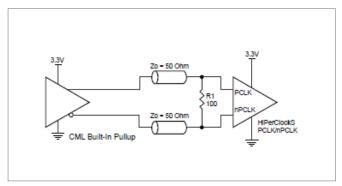


FIGURE 2B. PCLK/nPCLK INPUT DRIVEN
BY A BUILT-IN PULLUP CML DRIVER

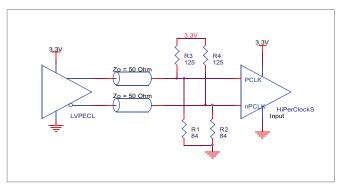


FIGURE 2C. PCLK/nPCLK INPUT DRIVEN
BY A 3.3V LVPECL DRIVER

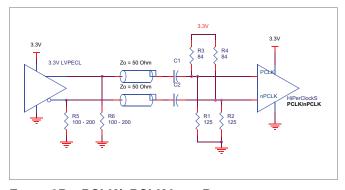


FIGURE 2D. PCLK/nPCLK INPUT DRIVEN
BY A 3.3V LVPECL DRIVER WITH AC COUPLE

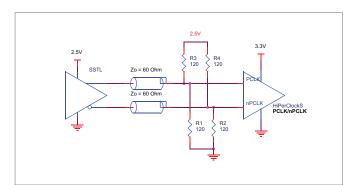


FIGURE 2E. PCLK/nPCLK INPUT DRIVEN BY AN SSTL DRIVER

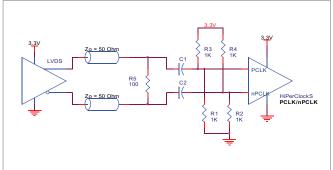


FIGURE 2F. PCLK/nPCLK INPUT DRIVEN
BY A 3.3V LVDS DRIVER



## **RELIABILITY INFORMATION**

Table 6.  $\theta_{\text{JA}} \text{vs. Air Flow Table for 32 Lead LQFP}$ 

#### θJA by Velocity (Linear Feet per Minute)

 O
 200
 500

 Single-Layer PCB, JEDEC Standard Test Boards
 67.8°C/W
 55.9°C/W
 50.1°C/W

 Multi-Layer PCB, JEDEC Standard Test Boards
 47.9°C/W
 42.1°C/W
 39.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

#### TRANSISTOR COUNT

The transistor count for 83940D is: 820



#### PACKAGE OUTLINE - Y SUFFIX FOR 32 LEAD LQFP

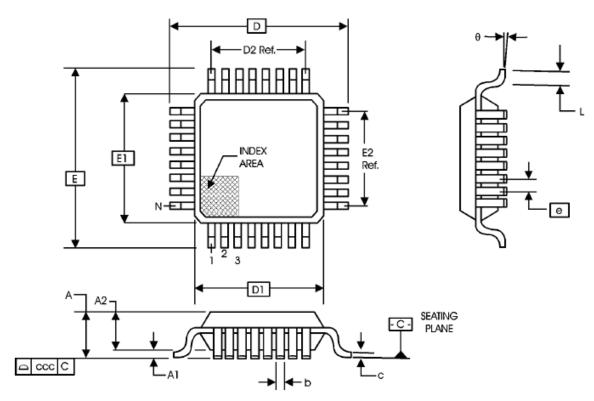


TABLE 7. PACKAGE DIMENSIONS

	JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS						
CYMPOL	ВВА						
SYMBOL	MINIMUM	MINIMUM NOMINAL					
N		32					
Α			1.60				
A1	0.05		0.15				
A2	1.35	1.40	1.45				
b	0.30	0.37	0.45				
С	0.09		0.20				
D		9.00 BASIC					
D1		7.00 BASIC					
D2		5.60 Ref.					
E		9.00 BASIC					
E1		7.00 BASIC					
E2		5.60 Ref.					
е		0.80 BASIC					
L	0.45	0.60	0.75				
θ	0°		7°				
ccc			0.10				

Reference Document: JEDEC Publication 95, MS-026



#### Table 8. Ordering Information

Part/Order Number	Marking	Package	Shipping Pack- aging	Temperature
83940DYLF	ICS83940DYLF	32 Lead "Lead Free" LQFP	Tray	0°C to 70°C
83940DYLFT	ICS83940DYLF	32 Lead "Lead Free" LQFP	Tape and Reel	0°C to 70°C

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REVISION HISTORY SHEET				
Rev	Table	Page	Description of Change	Date
А	T5A	4	3.3V AC Characteristics table - • tsk(pp) Test Conditions, replaced "<" with " $\leq$ "; corrected Units to "ns" from "ps". • odc - corrected Test Conditions to read "134MHz $\leq$ f $\leq$ 250MHz", from "f $\leq$ 250MHz".	
	T5B	5	3.3V/2.5V AC Characteristics table - tsk(pp) Test Conditions, replaced "<" with " $\leq$ "; corrected Units to read "ns" from "ps".	10/11/02
	T5C	6	2.5V AC Characteristics table - tsk(pp) Test Conditions, replaced "<" with " $\leq$ "; corrected Units to "ns" from "ps".	
А	T2	2	Pin Characteristics table - changed R <sub>OUT</sub> 25Ω maximum to 28Ω maximum.  Delete R <sub>PULLUP</sub> row.  3.3V Output Load AC Test Circuit diagram - corrected GND equation to read -1.65V from -1.165V	12/12/02
		7	Added LVTTL to title. Updated format.	
В	T1 T2 T5A T5B T5C	2 4 5 6 7 10	Pin Description Table - added Pullup and Pulldown to Pin 6, nPCLK.  Pin Characteristics Table - added R <sub>PULLUP</sub> row.  Added tjit row.  Added tjit row.  Added tjit row.  Added Additive Phase Jitter section.  Updated Single Ended Signal Driving Differential Input diagram.  Added LVPECL Clock Interface section.	10/9/03
В	T5A - T5C	1 4 - 6 11 14	Added "Lead-Free" bullet to Features section. Added NOTE 7. Updated LVPECL Clock Input Interface section. Ordering Information table - added "Lead-Free" part number.	6/15/04
В	Т8	14 16	Updated datasheet's header/footer with IDT from ICS. Removed ICS prefix from Part/Order Number column. Added Contact Page.	8/9/10
В	Т8	14	Ordering Information - Removed leaded devices. Updated data sheet format.	3/25/15



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